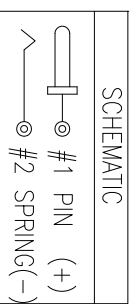
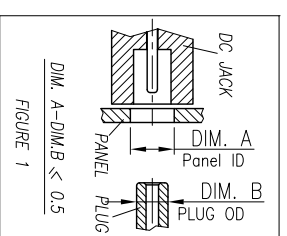
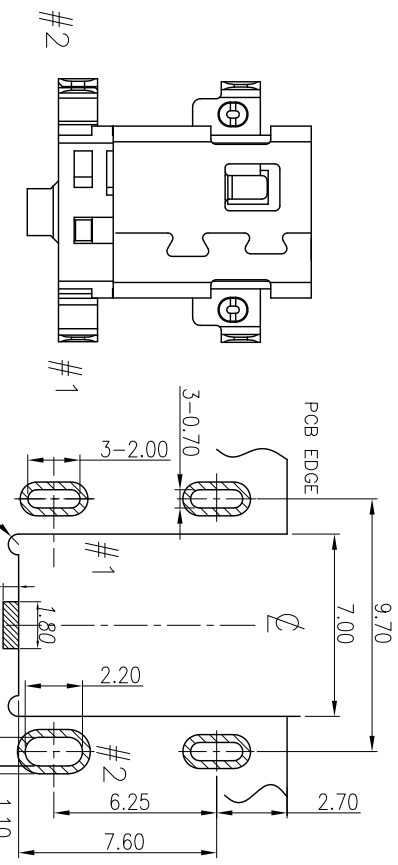
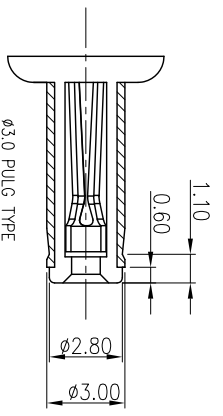
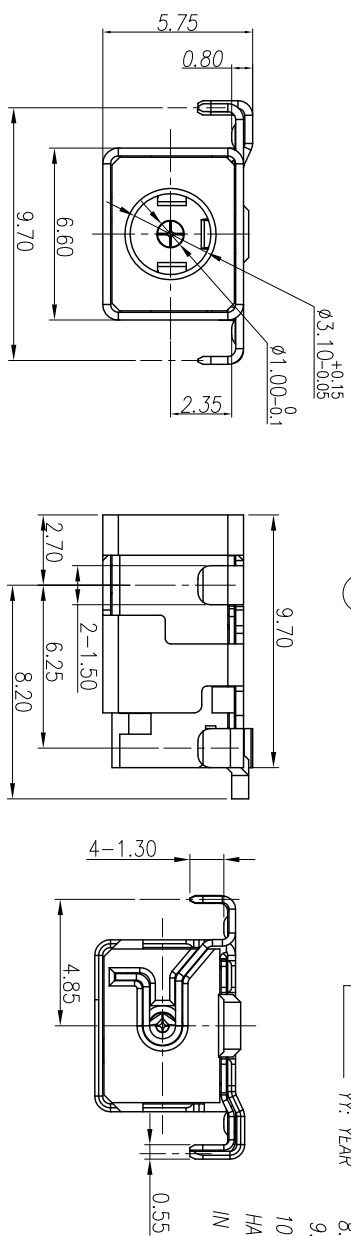
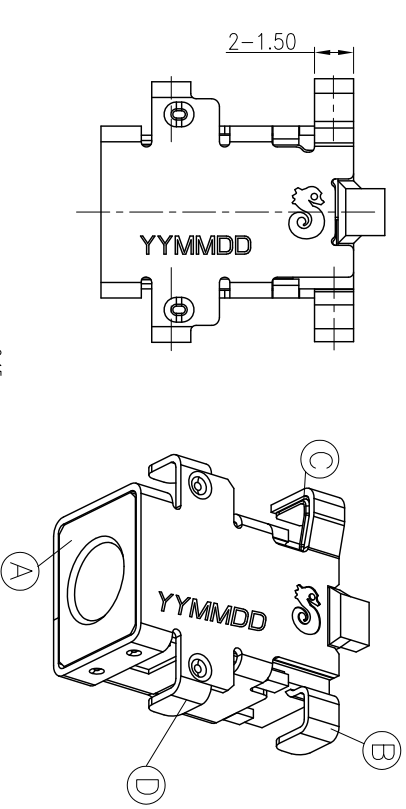


| REV. | ECN NO. | OR. DESCRIPTION | REVISED | DATE |
|------|-------------------|-----------------|----------|------------|
| A | PDR NO.TT30715-1A | | Springwu | 2013.10.16 |



SPECIFICATIONS:

- ELECTRICAL CHARACTERISTICS:
 - RATING: 20V 3.5A;
 - CONTACT RESISTANCE: 30mΩ MAX.(INITIAL)
 - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE.
 - INSULATION RESISTANCE: 100MΩ MIN. MEASURED BY 500 VDC
- MECHANICAL CHARACTERISTICS:
 - INSERTION FORCE : 3.0KGF. MAX.;
 - WITHDRAWAL FORCE : 0.4~3.0KGF.;
 - LIFE TEST: 5,000 CYCLES MIN.
 - OTHER GENERAL SPEC. TO REFER "2DC3082-011111F" SPEC."
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK: (C)
 - HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING: (E)
 - FOR REFLOW SOLDERING LEAD-FREE PROCESS.
 - PRINTED DATE CODE "YYMMDD" ON TOP OF CONNECTOR.
 - THE PANEL'S ID MUST BE GREATER THAN THE PLUG'S OD WHICH MUST HAVE A DIFFERENCE OF LESS THAN OR BE EQUAL TO 0.5 mm.(AS SHOWN IN FIGURE 1.)



| | | | | | |
|--|-------------|-----|--|-------|--|
| D | SHELL | 1 | STAINLESS | 0.3T | N: 80μ MIN |
| C | SPRING | 1 | COPPER ALLOY | 0.2T | Sn 80μ OVER N: 50μ MIN. |
| B | PIN | 1 | COPPER ALLOY | 0.25T | GOLD FLASH ON CONTACT AREA Sn 120μ MIN PLATED ON SOLDER TAIL; ALL OVER N: 50μ MIN. |
| A | BODY | 1 | HIGH THERMOPLASTIC (HALOGEN FREE) UL94V-0 | | BLACK |
| NO | DESCRIPTION | QTY | MATERIAL | | PLATING & COLOR |
| UNLESS OTHERWISE SPECIFIED TOLERANCES | | | | | |
| DECIMALS: ANGLES: | | | | | |
| X | :±0.5 | X | :±2° | | |
| X.X | :±0.3 | X.X | :±1° | | |
| X.XX | :±0.2 | | | | |
| TITLE: DC POWER JACK | | | | | |
| DWG: Springwu PART NO. 2DC3082-011111F | | | | | |
| CHKD: Sky SCALE 5:1 UNIT: mm | | | | | |
| APVD: Lussen SIZE: A3 SHEET: 1 OF 1 REV: A | | | | | |

Singatron Enterprise Co., Ltd.
信安達企業股份有限公司

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